



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

** : Required Field*

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2015-05-18
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	IPD MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STF5N95K3	TSFP*VPL3B62	A	SHENZHEN B/E	2015-05-18
Amount	UoM	Unit type	ST ECOPACK Grade	
1900.00	mg	Each	ECOPACK2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
NAC	NAC	NAC		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	NAC	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SIP	10, 9.05, 4.4	3	THROUGH HOLE	
Comment	Package: TO 220 ISO FULL PACK IN LINE; MD valid for CP:STF5N95K3.			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-17th December 2014				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	TSFP*VPL3B62					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or Dies (choose)	Other inorganic materials	7.880	mg	supplier	die	Silicon (Si)	7440-21-3		7.555	mg	958762	3977
				supplier	metallization	Aluminium (Al)	7429-90-5		0.147	mg	18652	77
				supplier	Passivation	Silicon Nitride	12033-89-5		0.036	mg	4568	19
				supplier	Passivation	Silicon Oxide	7631-86-9		0.075	mg	9517	39
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.004	mg	508	2
				supplier	back side metallization	Gold (Au)	7440-57-5		0.011	mg	1396	6
Leadframe	Copper & its alloys	647.130	mg	supplier	back side metallization	Nickel (Ni)	7440-02-0		0.052	mg	6598	27
				supplier	alloy	Copper (Cu)	7440-50-8		643.472	mg	994347	338669
				supplier	alloy	Iron (Fe)	7439-89-6		0.644	mg	995	339
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.193	mg	298	102
				supplier	metallization	Nickel (Ni)	7440-02-0		2.804	mg	4333	1476
Soft solder	Solder	7.218	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	6.894	mg	955112	3628
				supplier	solder	Silver (Ag)	7440-22-4		0.180	mg	24938	95
				supplier	solder	Tin (Sn)	7440-31-5		0.144	mg	19950	76
				supplier	wire	Aluminium (Al)	7429-90-5		0.783	mg	998724	412
Bonding wires	Other inorganic materials	0.784	mg	supplier	wire	Magnesium (Mg)	7439-95-4		0.001	mg	1276	1
				supplier	wire							
Encapsulation	Other Organic Materials	1230.626	mg	supplier	mold compound	Quartz	14808-60-7		861.438	mg	700000	453388
				supplier	mold compound	Silica, vitreous	60676-86-0		92.297	mg	75000	48577
				supplier	mold compound	Epoxy resin	proprietary		172.288	mg	140000	90678
				supplier	mold compound	phenol resin	Proprietary		86.144	mg	70000	45339
				supplier	mold compound	metal hydroxide	Proprietary		12.306	mg	10000	6477
connections coating	Solder	6.362	mg	supplier	mold compound	carbon black	1333-86-4		6.153	mg	5000	3238
				supplier	solder alloy	Tin (Sn)	7440-31-5		6.362	mg	1000000	3348